

ABSTRACT**PROCESS FOR PRODUCING ELECTRICAL CONTACTING PADS ON A SUBSTRATE AND DEVICE FOR CARRYING OUT THIS PROCESS**

The invention relates to a process for producing at least one electrical contacting pad on a receiving zone (2) of an electronic component, in which:

- a liquid alloy (4) is injected into at least one channel (5) comprising a feed portion (5A) and a molding portion (5B) which are separated by a narrowing, said channel (5) being positioned in such a way that the molding portion (5B) opens on the receiving zone (2),
- the molding portion (5B) is separated from the receiving zone (2) before complete solidification of the metal or alloy (4), while the feed (5A) and molding (5B) portions remain joined,

which process is characterized in that the feed portion (5A) is part of a first part forming a die (6), and the molding portion (5B) is part of a second separate part forming a mold (7), said die and mold being juxtaposed to form the channel (5).

Production of connection contacting pads for electronic components.

Translation of the title and the abstract as they were when originally filed by the Applicant. No account has been taken of any changes that may have been made subsequently by the PCT Authorities acting ex officio, e.g. under PCT Rules 37.2, 38.2, and/or 48.3.